## 506650511 05/07/2021

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	EXECUTIVE ORDER 9424, CONFIRMATORY LICENSE	

#### **CONVEYING PARTY DATA**

Name	Execution Date
DEERE & COMPANY	08/13/2020

#### **RECEIVING PARTY DATA**

Name:	UNITED STATES DEPARTMENT OF ENERGY	
Street Address:	1000 INDEPENDENCE AVE. S.W.	
City:	WASHINGTON	
State/Country:	D.C.	
Postal Code:	20585	

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14700655

#### **CORRESPONDENCE DATA**

**Fax Number:** (630)252-2779

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** (630) 252-2137

Email: Confirmatory.License@science.doe.gov

**Correspondent Name:** TIMOTHY L HARNEY **Address Line 1:** 9800 S. CASS AVE

Address Line 2: IPLD

Address Line 4: ARGONNE, ILLINOIS 60439

ATTORNEY DOCKET NUMBER:	14/700,655 PSL
NAME OF SUBMITTER:	PAULA S LEON
SIGNATURE:	/Paula S Leon/
DATE SIGNED:	05/07/2021

**Total Attachments: 1** 

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PATENT 506650511 REEL: 057269 FRAME: 0309

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**RECORDED: 05/07/2021** 

Sign and submit	the executed document to the appropriate funding ag	ency (e.g., upload in iEdison).		
Invention Title:	PACKAGE FOR A SEMICONDUCTOR D	EVICE		
Inventor(s):	Christopher J. Schmit; Brij N. Singh			
U.S. Filing/Issu	ue Date: April 30, 2015/ February 7, 2017			
Patent or Appli	cation Serial No.: 9,564,385			
	Number(s): DE-EE0006521			
Foreign Applica	ations filed/intended in (countries): CN, DE, GB	<del></del>		
at 37 CFR 401. identified grant	14, FAR 52.227-11 or FAR 52.227-12 (if applica or contract award from the United States Govern	I.S.C. 200, et seq., and the Standard Patent Rights clause ble) which are included among the terms of the above iment. This document is confirmatory of:		
United State continuation  2. All other rigulation	ates the invention described in any patent applications in part, and in any and all patents and re-issing the acquired by the Government by reason of the that are applicable to the award.	ation and in any and all divisions, continuations, and ues granted thereon throughout the world; and he above identified grant/contract award and the laws and		
application.	int is hereby granted an irrevocable power to insp	pect and make copies of the above-identified patent		
Signed this	13 day of AUGUS	T/1,20,2011/2		
	s C. Muszalski	MAN IMMINA		
	nstitutional Business Official)	(Signature)		
Title Directo	or, Module & Electric Systems Engi	neering		
For Deere	& Company			
	(Grantee/Contractor Organization)			
At One Jo	hn Deere Place			
Moline,	Illinois 61265			
	(Business Address)			
Signed this	1 G. Kallis	<u>31</u>		
Бу		Al-CACULA		
	nstitutional Business Official)	(Signature)		
<sub>Title</sub> Mana	iger Advanced Technology			
<sub>For</sub> John [	Deere Electronic Solutions, Inc.			
	(Grantee/Contractor Organization)			
At 1750 N	IDSU Research Park Drive			
Fargo,	North Dakota 58102			
	(Rusiness Address)			

PATENT REEL: 057269 FRAME: 0310